



Material Content Data Sheet



Sales Product Name		TLF4949EJ		Issued		1. August 2018		
MA#		MA001001408						
Package		PG-DSO-8-52		Weight*		83.61 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.577	0.69	0.69	6902	6902
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		109	
	non noble metal	zinc	7440-66-6	0.036	0.04		435	
	non noble metal	iron	7439-89-6	0.728	0.87		8704	
wire	non noble metal	copper	7440-50-8	29.548	35.34	36.26	353406	362654
	non noble metal	copper	7440-50-8	0.086	0.10	0.10	1029	1029
	organic material	carbon black	1333-86-4	0.102	0.12		1218	
encapsulation	plastics	epoxy resin	-	4.686	5.60		56042	
	inorganic material	silicondioxide	60676-86-0	46.142	55.20	60.92	551891	609151
leadfinish	non noble metal	tin	7440-31-5	0.695	0.83	0.83	8314	8314
plating	noble metal	silver	7440-22-4	0.725	0.87	0.87	8665	8665
glue	plastics	epoxy resin	-	0.069	0.08		821	
	noble metal	silver	7440-22-4	0.206	0.25	0.33	2464	3285
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com